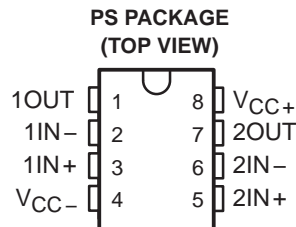


- Wide Range of Supply Voltages; Single Supply . . . 3 V to 36 V, or Dual Supplies
- Class AB Output Stage
- High-Impedance N-Channel-JFET Input Stage . . .  $10^{12} \Omega$  Typ
- Internal Frequency Compensation
- Short-Circuit Protection
- Input Common Mode Includes  $V_{CC-}$
- Low Input Offset Current . . . 50 pA
- Low Input Bias Current . . . 200 pA Typ



## description

The TL092 JFET-input operational amplifier is similar in performance to the MC3403 family, but with much higher input impedance derived from a FET input stage. The N-channel-JFET input stage allows a common-mode input voltage range that includes the negative supply voltage and offers a typical input impedance of  $10^{12} \Omega$ , a typical input offset current of 50 pA, and a typical input bias current of 200 pA. This device is designed to operate from a single supply over a range of 3 V to 36 V. Operation from split supplies also is possible, provided the difference between the two supplies is 3 V to 36 V. Output voltage range is from  $V_{CC-}$  to  $V_{CC+} - 1.3$  V, with a load resistor to  $V_{CC-}$ .

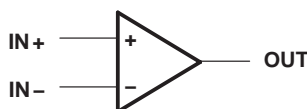
The TL092 is characterized for operation from 0°C to 70°C.

### AVAILABLE OPTIONS

$T_A$	PACKAGED DEVICE
	PLASTIC SMALL OUTLINE (PS)
0°C to 70°C	TL092CPSR

The PS package is only available taped and reeled. Add the suffix R to device type for ordering (e.g., TL092CPSR).

## symbol



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS  
INSTRUMENTS**

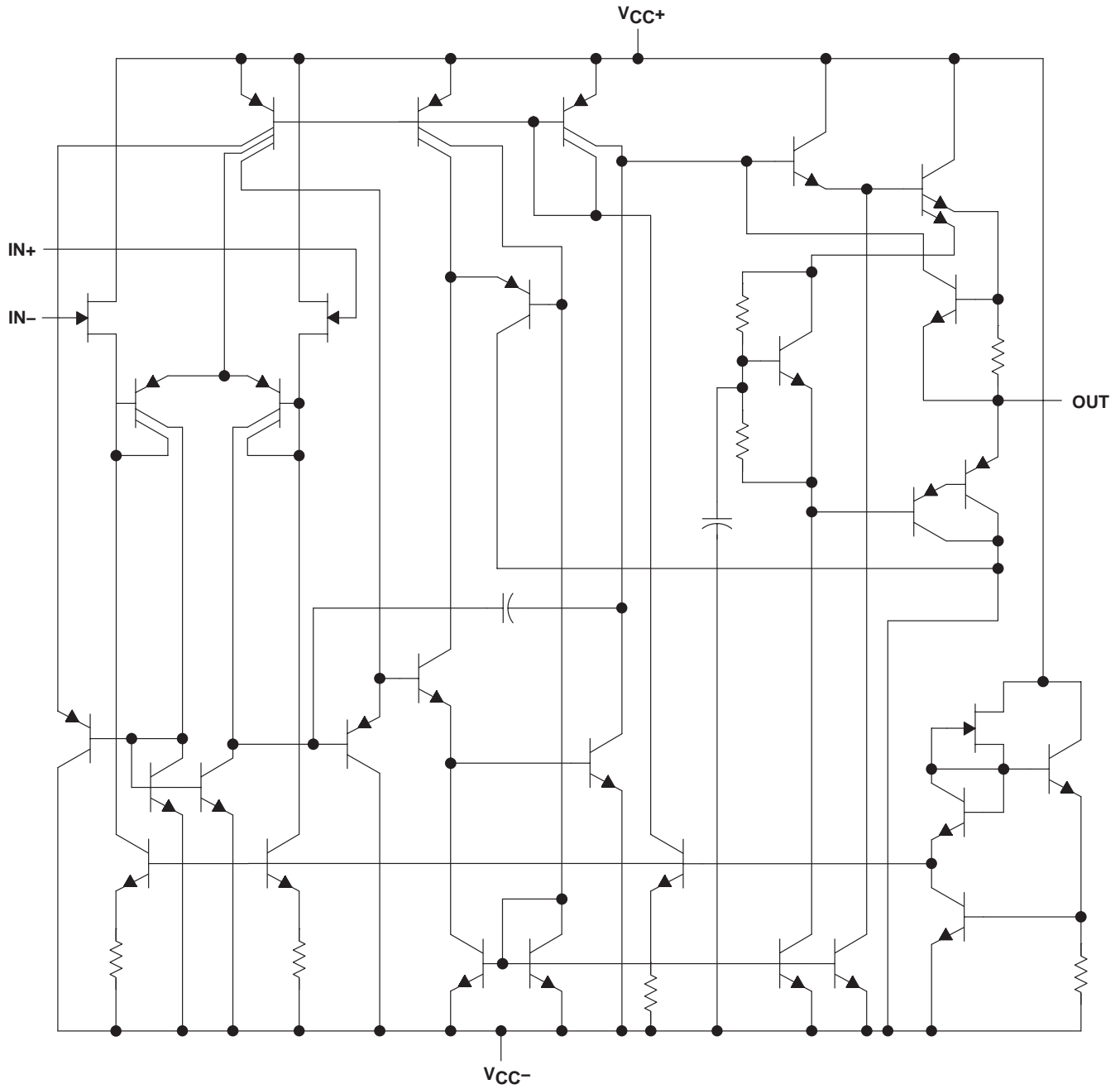
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# TL092 DUAL JFET-INPUT OPERATIONAL AMPLIFIER

SLOS372 – JUNE 2001

## schematic



**absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†**

Supply voltage: $V_{CC+}$ (see Note 1) .....	18 V
$V_{CC-}$ (see Note 1) .....	–18 V
$V_{CC+}$ with respect to $V_{CC-}$ .....	36 V
Differential input voltage, $V_{ID}$ (see Note 2) .....	±36 V
Input voltage, $V_I$ (see Notes 1 and 3) .....	±18 V
Package thermal impedance, $\theta_{JA}$ (see Notes 4 and 5) .....	95°C/W
Lead temperature 1.6 mm (1/16 inch) from case for 10 seconds .....	260°C
Storage temperature range, $T_{stg}$ .....	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES:
1. All voltage values, except differential voltages, are with respect to the midpoint between  $V_{CC+}$  and  $V_{CC-}$ .
  2. Differential voltages are at the noninverting input with respect to the inverting input.
  3. Neither input must ever be more positive than  $V_{CC+}$  or more negative than  $V_{CC-} - 0.3$  V.
  4. Maximum power dissipation is a function of  $T_J(\text{max})$ ,  $\theta_{JA}$ , and  $T_A$ . The maximum allowable power dissipation at any allowable ambient temperature is  $P_D = (T_J(\text{max}) - T_A)/\theta_{JA}$ . Operating at the absolute maximum  $T_J$  of 150°C can impact reliability.
  5. The package thermal impedance is calculated in accordance with JESD 51-7.

**recommended operating conditions**

	MIN	MAX	UNIT
$V_{CC\pm}$ Supply voltage	3	36	V
$T_A$ Operating free-air temperature range	0	70	°C

# TL092

## DUAL JFET-INPUT OPERATIONAL AMPLIFIER

SLOS372 – JUNE 2001

**electrical characteristics at specified free-air temperature,  $V_{CC\pm} = \pm 15\text{ V}$   
(all characteristics are specified under open-loop conditions, unless otherwise noted)**

PARAMETER		TEST CONDITIONS		$T_A$	MIN	TYP†	MAX	UNIT
$V_{IO}$	Input offset voltage	$R_S = 50\ \Omega$		25°C		5	15	mV
				Full range			20	
$\alpha_{V_{IO}}$	Temperature coefficient of input offset voltage			25°C		10		$\mu\text{V}/^\circ\text{C}$
$I_{IO}\ddagger$	Input offset current			25°C		50	200	pA
				Full range			5	nA
$I_{IB}\ddagger$	Input bias current			25°C		200	400	pA
				Full range			10	nA
$V_{ICR}$	Common-mode input voltage range			25°C	$V_{CC-}$ to 12	$V_{CC-}$ to 13		V
$V_{O(PP)}$	Peak output voltage swing			25°C	$R_L = 2\ \text{k}\Omega$	$\pm 10$	$\pm 13$	V
				25°C	$R_L = 10\ \text{k}\Omega$	$\pm 12$	$\pm 13.5$	
				Full range	$R_L = 2\ \text{k}\Omega$	$\pm 10$		
$A_{VD}$	Large-signal differential voltage amplification	$R_L = 2\ \text{k}\Omega$	$V_O = \pm 10\ \text{V}$	25°C		20	200	V/mV
				Full range		15		
$B_{OM}$	Maximum output swing bandwidth	$R_L = 2\ \text{k}\Omega$	$V_{O(PP)} = 20\ \text{V}$ , THD < 5%	25°C		9		kHz
$B_1$	Unity gain bandwidth	$R_L = 10\ \text{k}\Omega$	$V_O = 50\ \text{mV}$	25°C		1		MHz
$\phi_m$	Phase margin	$R_L = 2\ \text{k}\Omega$	$C_L = 200\ \text{pF}$	25°C		60°		
$r_i$	Input resistance	$f = 20\ \text{Hz}$		25°C		$10^{12}$		$\Omega$
$r_o$	Output resistance	$f = 20\ \text{Hz}$		25°C		75		$\Omega$
CMRR	Common-mode rejection ratio	$R_S = 50\ \Omega$	$V_{IC} = V_{ICR}$	25°C		70	90	dB
$k_{SVR}$	Supply-voltage rejection ratio ( $\Delta V_{CC}/\Delta V_{IO}$ )	$R_S = 50\ \Omega$	$V_{CC\pm} = \pm 3\ \text{V}$ to $\pm 15\ \text{V}$	25°C		75	90	dB
$I_{OS}$	Short-circuit output current			25°C		40		mA
$I_{CC}$	Supply current (per amplifier)	$V_O = 0$	No load	25°C		1.5	2.5	mA

† All typical values are at  $T_A = 25^\circ\text{C}$ .

‡ Input bias currents of a FET-input operational amplifier are normal junction reverse currents, which are temperature sensitive. Pulse techniques that maintain the junction temperature as close to the ambient temperature as possible must be used.

**electrical characteristics at specified free-air temperature,  $V_{CC+} = 5\ \text{V}$ ,  $V_{CC-} = 0\ \text{V}$ ,  $T_A = 25^\circ\text{C}$   
(unless otherwise noted)**

PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT
$V_{IO}$	Input offset voltage	$R_S = 50\ \Omega$	$V_O = 2.5\ \text{V}$		5	15	mV
$I_{IO}$	Input offset current		$V_O = 2.5\ \text{V}$		50	200	pA
$I_{IB}$	Input bias current		$V_O = 2.5\ \text{V}$		200	400	pA
$V_{O(PP)}$	Peak output voltage swing	$R_L = 10\ \text{k}\Omega$		3.3	3.5		V
		$R_L = 10\ \text{k}\Omega$	$V_{CC+} = 5\ \text{V}$ to $30\ \text{V}$	$V_{CC+} - 1.7$			V
$A_{VD}$	Large-signal differential voltage amplification	$R_L = 2\ \text{k}\Omega$	$\Delta V_O = 1.6\ \text{V}$	20	200		V/mV
$k_{SVR}$	Supply-voltage rejection ratio ( $\Delta V_{CC}/\Delta V_{IO}$ )	$R_S = 50\ \Omega$	$V_{CC\pm} = \pm 3\ \text{V}$ to $\pm 15\ \text{V}$	75			dB
$I_{CC}$	Supply current (per amplifier)	$V_O = 2.5\ \text{V}$	No load		1.5	2.5	mA
$V_{O1}/V_{O2}$	Channel separation		$f = 1\ \text{kHz}$ to $20\ \text{kHz}$		120		dB

† All typical values are at  $T_A = 25^\circ\text{C}$ .



operating characteristics,  $V_{CC\pm} = \pm 15\text{ V}$ ,  $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
SR	Slew rate at unity gain $V_I = \pm 10\text{ V}$ (see Figure 1), $C_L = 100\text{ pF}$ , $R_L = 2\text{ k}\Omega$		0.6		$\text{V}/\mu\text{s}$
$t_r$	Rise time $\Delta V_O = 50\text{ mV}$ (see Figure 1), $C_L = 100\text{ pF}$ , $R_L = 2\text{ k}\Omega$		0.2		$\mu\text{s}$
$t_f$	Fall time $\Delta V_O = 50\text{ mV}$ (see Figure 1), $C_L = 100\text{ pF}$ , $R_L = 2\text{ k}\Omega$		0.2		$\mu\text{s}$
	Overshoot factor $\Delta V_O = 50\text{ mV}$ (see Figure 1), $C_L = 100\text{ pF}$ , $R_L = 2\text{ k}\Omega$		20%		
	Crossover distortion $V_{I\text{PP}} = 30\text{ mV}$ , $V_{O(\text{PP})} = 2\text{ V}$ , $f = 10\text{ kHz}$		1%		
$V_n$	Equivalent input noise voltage $R_S = 100\ \Omega$ , $f = 1\text{ kHz}$		34		$\text{nV}/\sqrt{\text{Hz}}$

### PARAMETER MEASUREMENT INFORMATION

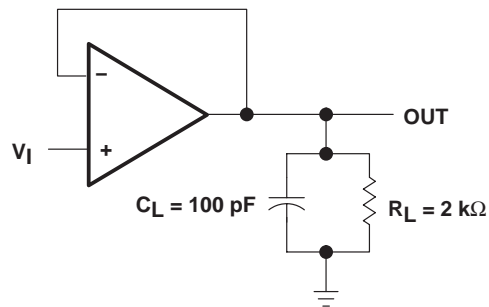


Figure 1. Unity-Gain Amplifier

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
TL092CPSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL092CPSRE4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL092CPSRG4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBsolete:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

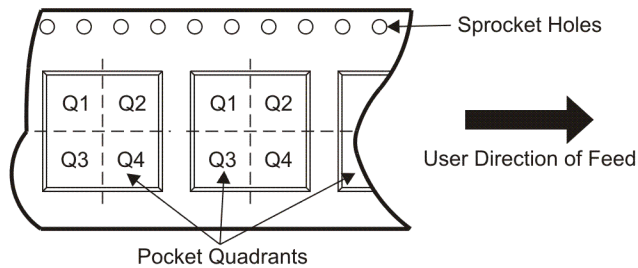
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**TAPE AND REEL INFORMATION**



**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL092CPSR	SO	PS	8	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1

**TAPE AND REEL BOX DIMENSIONS**



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL092CPSR	SO	PS	8	2000	346.0	346.0	33.0



## MECHANICAL DATA

PS (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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